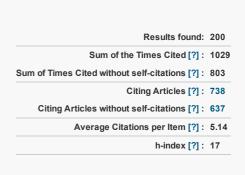


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 Stability, causality, and passivity in electrical intercol models By: Triverio, Piero; Grivet-Talocia, Stefano; Nakhla, Michel S.; IEEE TRANSACTIONS ON ADVANCED PACKAGING Volum Pages: 795-808 Published: NOV 2007 	et al.	2 7	8	6	1	98	8.91
2. Transient analysis of lossy transmission lines: An effapproach based on the method of characteristics By: Grivet-Talocia, S; Huang, HM; Ruehli, AE; et al. Conference: IEEE 11th Topical Meeting on Electrical Performant Electronic Packaging Location: MONTEREY, CA Date: OCT 21 Sponsor(s): IEEE Microwave Theory & Techn Soc; IEEE Compackaging & Mfg Technol Soc IEEE TRANSACTIONS ON ADVANCED PACKAGING Voluming Pages: 45-56 Published: FEB 2004	nce of -23, 2002 2 ponents,	3	4	2	0	77	5.50
3. M pi log, macromodeling via parametric identification gates By: Stievano, IS; Maio, IA; Canavero, FG Conference: IEEE 11th Topical Meeting on Electrical Performant Electronic Packaging Location: MONTEREY, CA Date: OCT 21 Sponsor(s): IEEE Microwave Theory & Techn Soc; IEEE Compackaging & Mfg Technol Soc IEEE TRANSACTIONS ON ADVANCED PACKAGING Voluming Pages: 15-23 Published: FEB 2004	nce of -23, 2002 3 ponents,	3	5	6	1	58	4.14
4. Parameters Variability Effects on Multiconductor Interconnects via Hermite Polynomial Chaos By: Stievano, Igor Simone; Manfredi, Paolo; Canavero, Flavio IEEE TRANSACTIONS ON COMPONENTS PACKAGING ANI MANUFACTURING TECHNOLOGY Volume: 1 Issue: 8 Pa Published: AUG 2011		8	8	10	1	47	6.71

5.	Parametric macromodels of digital I/O ports By: Stievano, IS; Maio, IA; Canavero, FG Conference: 10th Topical Meeting on Electrical Performance of Electronic Packaging Location: CAMBRIDGE, MA Date: OCT 29-31, 2001 Sponsor(s): IEEE Microwave Theory & Techn Soc; IEEE Components, Packaging & Mfg Technol Soc IEEE TRANSACTIONS ON ADVANCED PACKAGING Volume: 25 Issue: 2 Pages: 255-264 Published: MAY 2002	1	0	2	1	0	45	2.81
6.	Stochastic Modeling-Based Variability Analysis of On-Chip Interconnects By: Vande Ginste, Dries; De Zutter, Daniel; Deschrijver, Dirk; et al. IEEE TRANSACTIONS ON COMPONENTS PACKAGING AND MANUFACTURING TECHNOLOGY Volume: 2 Issue: 7 Pages: 1182-1192 Published: JUL 2012	12	12	11	4	0	44	7.33
7.	Stochastic Analysis of Multiconductor Cables and Interconnects By: Stievano, Igor S.; Manfredi, Paolo; Canavero, Flavio G. IEEE TRANSACTIONS ON ELECTROMAGNETIC COMPATIBILITY Volume: 53 Issue: 2 Pages: 501-507 Published: MAY 2011	4	9	11	10	1	40	5.71
8.	Theoretical assessment of bulk current injection versus radiation By: Pignari, S; Canavero, FG IEEE TRANSACTIONS ON ELECTROMAGNETIC COMPATIBILITY Volume: 38 Issue: 3 Pages: 469-477 Published: AUG 1996	5	4	1	6	0	37	1.68
9.	Overview of Signal Integrity and EMC Design Technologies on PCB: Fundamentals and Latest Progress By: Wu, Tzong-Lin; Buesink, Frits; Canavero, Flavio IEEE TRANSACTIONS ON ELECTROMAGNETIC COMPATIBILITY Volume: 55 Issue: 4 Pages: 624-638 Published: AUG 2013	0	5	17	12	0	34	6.80
10.	Analysis of crosstalk and field coupling to lossy MTL's in a SPICE environment By: Maio, I; Canavero, FG IEEE TRANSACTIONS ON ELECTROMAGNETIC COMPATIBILITY Volume: 38 Issue: 3 Pages: 221-229 Published: AUG 1996	2	0	0	0	0	27	1.23
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